CLAIMS

1. An electronic device sealing resin sheet, having a probe tack of 5 g to 500 g at 25°C and a tensile storage elastic modulus of 2 MPa to 10^3 MPa at 25°C, the tack being measured, using a probe having a diameter of 25 mm.

2. The electronic device sealing resin sheet according to claim 1, having a surface roughness (Ra) of 400 nm or less.

3. The electronic device sealing resin sheet according to claim 1 or 2, comprising an inorganic filler, and

the content of the inorganic filler in the resin sheet being from 60 to 90% by volume.

4. The electronic device sealing resin sheet according to any one of claims 1 to 3, comprising an epoxy resin, and

the epoxy resin having a softening point of 100°C or lower.

5. The electronic device sealing resin sheet according to any one of claims 1 to 4, which is used to seal the electronic device that is an electronic device arranged in a vacuum package container.

6. The electronic device sealing resin sheet according to any one of claims 1 to 4, which is used to a

method for manufacturing an electronic-device package that comprises the step of arranging the resin sheet over the electronic device mounted over a substrate,

the step of putting, into a vacuum package container, the electronic device mounted over the substrate and the resin sheet arranged over the electronic device, and

the step of sealing the electronic device in the vacuum package container with the resin sheet.

7. The electronic device sealing resin sheet according to claim 5 or 6, wherein the electronic device is an SAW filter.

8. A method for manufacturing an electronic-device package, comprising the step of sealing an electronic device with a resin sheet having a probe tack of 5 g to 500 g at 25°C and a tensile storage elastic modulus of 2 MPa to 10^3 MPa at 25°C, the tack being measured, using a probe having a diameter of 25 mm.

9. The method for manufacturing an electronic-device package according to claim 8, further comprising the step of arranging the resin sheet over the electronic device mounted over a substrate, and

the step of putting, into a vacuum package container, the electronic device mounted over the substrate and the resin sheet arranged over the electronic device,

wherein in the step of sealing the electronic device, the electronic device in the vacuum package container is sealed with the resin sheet.